



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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Supplier Information

Company Name * STMicroelectronics	Company Unique ID	Unique ID Authority	Response Date * n/a	Response Document ID				
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *					
Authorized Representative * GIANFRANCO SANTANGELO	Title - Representative APM MD CHAMPION	Phone - Representative * n/a	Email - Representative * n/a	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
	L6230	A58C*UR40AA6	2010-08-13	A	MU1A	1,926	mg	Each
Alternate Recommendation	PowerSO 36 .430 BODY WIDTH			Alternate Item Comments	ECOPACK1/ROHS;ST Internal reference CD0026875			

Manufacturing Process Information

Terminal Plating / Grid Array Material Matte Tin (Sn) - annealed	Terminal Base Alloy CU Alloy	J-STD-020 MSL Rating 3	Peak Process Body Temperature 250 C	Max Time at Peak Temperature 30 seconds	Number of Reflow Cycles 3
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Comments

Disclaimer: While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and

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RoHS Material Composition Declaration

Declaration Type *

Simplified

RoHS Directive 2002/95/EC **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration *

3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any

Supplier Acceptance *

Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM	
											-	+		
A58C*UR40AA6	Integrated circuit	25.697	mg	Supplier	Silicon die	Silicon (Si)	7440-21-3		25.5	mg			992,33	
					Supplier	die metallization	Aluminium (Al)	7429-90-5		0.002	mg			78
							Copper (Cu)	7440-50-8		0.007	mg			272
							Titanium (Ti)	7440-32-6		0.004	mg			156
							Chromium (Cr)	7440-47-3		0.001	mg			39
							Gold (Au)	7440-57-5		0.004	mg			156
							Nickel (Ni)	7440-02-0		0.013	mg			506
					Supplier	Die coating	Gamma-butyrolactone	96-48-0		0.111	mg			4,320
							Polyhydroxyamide	55295-98-2		0.05	mg			1,946
							Alcoxysilane	proprietary		0.003	mg			117
		Aryl Silicilic Acid	proprietary		0.002	mg			78					
Leadframe	1,231.48	mg	supplier	alloy	Copper (Cu)	7440-50-8		1,229.889	mg			998,70		
					Iron (Fe)	7439-89-6		0.566	mg		460			
					Iron Phosphide (FeP)	26508-33-8		1.034	mg		840			
Leadframe coating	3.252	mg	supplier	coating	Silver (Ag)	7440-22-4		3.252	mg		1,000,0			
Die Attach	8.079	mg	A	Lead/Lead Compound	Lead (Pb)	7439-92-1	7a. Lead	7.877	mg			974,99		
					Silver (Ag)	7440-22-4		0.121	mg		14,977			
					Tin (Sn)	7440-31-5		0.081	mg		10,026			
Bonding wire	1.775	mg	Supplier	Bonding wire	Gold (Au)	7440-57-5		1.775	mg		1,000,0			
Encapsulation	647.214	mg	supplier	Moulding Compound	Silica, vitreous	60676-86-0		478.938	mg			739,99		
					expoxy resin	29690-82-2		58.249	mg		90,000			
					Epoxy Cresol Novolak	29690-82-2		7.767	mg		12,001			
					Phenol resin	9003-35-4		38.833	mg		60,000			

			supplier	Moulding Compound		Biphenyl epoxy resin	85954-11-6		38.833	mg			60,000
			B	Antimony/Antimony C		Antimony Trioxide	1309-64-4		12.944	mg			20,000
			B	Brominated Flame Ret		Brominated Epoxy Resin	68541-56-0		9.708	mg			15,000
						Carbon Black	1333-86-4		1.942	mg			3,001
Finishing	8.494	mg		supplier	connection coating	Tin (Sn)	7440-31-5		8.494	mg			1,000,0